

xLED

xLED-BRI-8030 Pin Fin LED Heat Sink Φ 80mm for Bridgelux

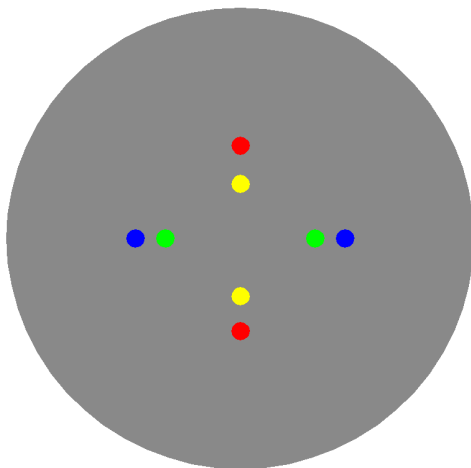
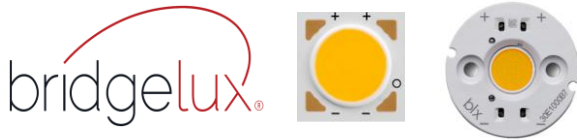
Features VS Benefits

- * The xLED-BRI-8030 Bridgelux Pin Fin LED Heat Sinks are specifically designed for luminaires using the Bridgelux LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 1,000 to 2,600 lumen.
- * Thermal resistance range R_{th} 3.13°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Bridgelux V Series™, Vero® SE Series, Vero® Series, H Series™ and Vesta™ Series LED engines.
- * Diameter 80.0mm - standard height 30.0mm, Other heights on request.
- * Forged from highly conductive aluminum.



Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Bridgelux COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.



Bridgelux LED Modules directly Mounting Options

Bridgelux V13,V15,V18 LED Array Series:

- | | |
|--------------------|--------------------|
| BXRE-20xxxxx-x-xx; | BXRE-40xxxxx-x-xx; |
| BXRE-27xxxxx-x-xx; | BXRE-50xxxxx-x-xx; |
| BXRE-30xxxxx-x-xx; | BXRE-57xxxxx-x-xx; |
| BXRE-35xxxxx-x-xx; | BXRE-65xxxxx-x-xx; |

With the Zhaga Book 3 Holders:
 BJB holder:47.319.2025.50; 47.319.2030.50;
 Direct mounting with machine screws M3x6.5mm, Blue indicator marks.

With the LEDiL products:
 Olivia series: FN14637-S;
 Ronda series: FN15xxx-xx;

Bridgelux Vero® Series Vero 10, Vero 13 LED Array and Vero® SE Series Vero 10 SE, Vero 13 SE LED Array

- | | |
|--------------------|--------------------|
| BXRC-27xxxxx-x-xx; | BXRC-50xxxxx-x-xx; |
| BXRC-30xxxxx-x-xx; | BXRC-57xxxxx-x-xx; |
| BXRC-35xxxxx-x-xx; | BXRC-65xxxxx-x-xx; |
| BXRC-40xxxxx-x-xx; | |

With the Bridgelux Holder:
 Direct mounting with machine screws M3x6.5mm.
 Vero 10 for the yellow indicator mark, Vero 13 for the red indicator mark.

With the LEDiL products:
 Olivia series: FN14637-S; FN14828-M;
 Ronda series: FN15xxx-xx;

Bridgelux® H Series™ H6, H9 LED Array:

- | | |
|--------------------|--------------------|
| BXRH-27xxxxx-x-xx; | BXRH-35xxxxx-x-xx; |
| BXRH-30xxxxx-x-xx; | BXRH-40xxxxx-x-xx; |

With the Zhaga Book 11 Holders:
 BJB holder:47.319.6120.50; 47.319.6104.50;
 Direct mounting with machine screws M3x6.5mm, Green indicator marks.
 With the LEDiL products: Ronda series: FN15xxx-xx;

Bridgelux® Vesta™ Series Dim-To-Warm 9mm Array

- BXRV-DR-1830H-1000-x-13;

With the Zhaga Book 11 Holders:
 BJB holder:47.319.6180.50;
 Direct mounting with machine screws M3x6.5mm, Green indicator marks.

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Mounting Options and Drawings & Dimensions

Example: xLED-BRI-8030-B-1,2

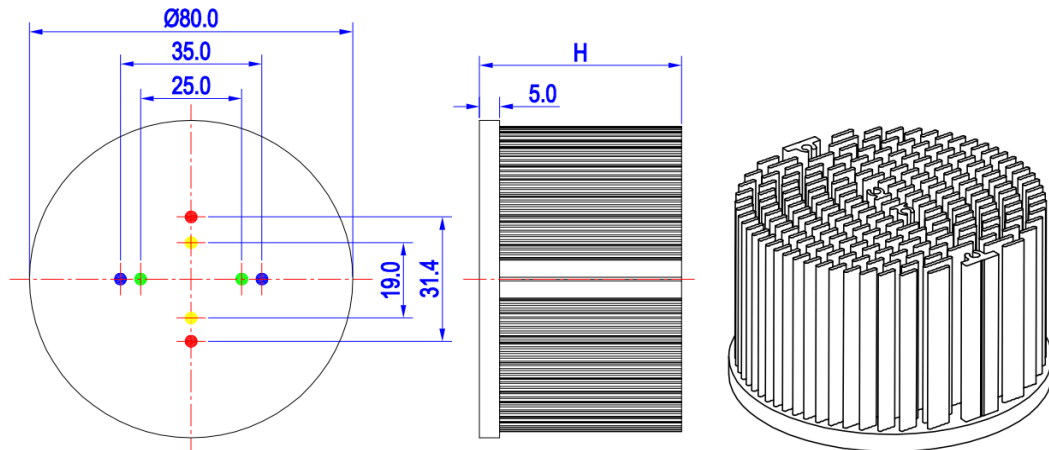
Example: xLED-BRI-80 **1** - **2** - **3**

- 1** Height (mm)
- 2** Anodising Color
 - B-Black
 - C-Clear
 - Z-Custom
- 3** Mounting Options - see graphics for details Combinations available
 - Ex.order code - 12
 - means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.


MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
			Olivia series	Ronda series			
1	Vero 10 Vero SE 10	Bridgelux	/	/	M3	6.5mm	19.0mm/ 2-@180°
2	Vesta™ Series 9mm	BJB Holder 47.319.6180.50	/	/	M3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
	H6	BJB Holder 47.319.6120.50	/	/			
	H9	BJB Holder 47.319.6104.50	/	FN15xxx-xx;			
3	Vero 13 Vero SE 13	Bridgelux	FN14637-S; FN14828-M;	FN15xxx-xx;	M3	6.5mm	31.4mm/ 2-@180°
4	V15, V18	BJB Holder 47.319.2224.50	FN14637-S	/	M3	6.5mm	35.0mm/ 2-@180° (Zhaga book3)
	V13	BJB Holder 47.319.2025.50		FN15xxx-xx;			



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The product data table

	Model No.	xLED-BRI-8030
	Heatsink Size	$\Phi 80 \times H 30\text{mm}$
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	140.0
	Dissipated power (T_{hs-amb},50°C)	16.0 (W)
	Cooling surface area (mm²)	72123
	Thermal Resistance (R_{hs-amb})	3.13 (°C/W)

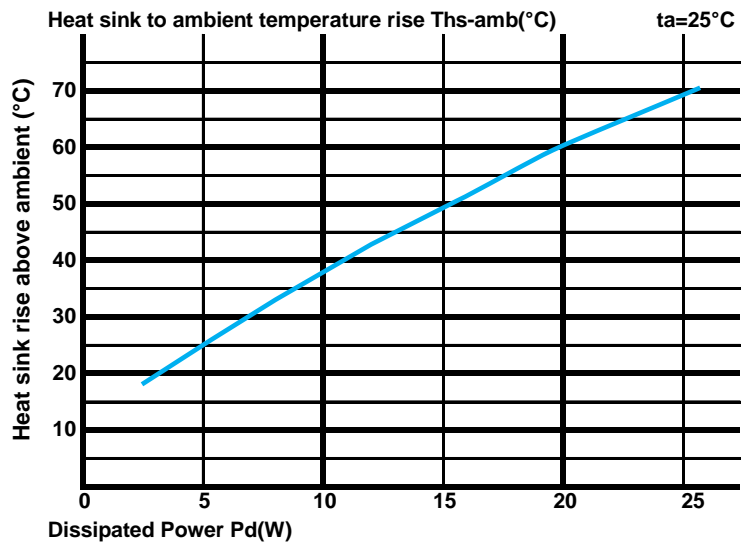
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: $P_d = P_e \times (1 - \eta_L)$.

Pd - Dissipated power ; Pe - Electrical power ; η_L = Light efficiency of the LED module;

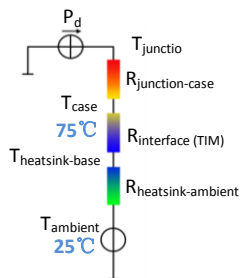
Dissipated Power Pd(W)	Pd = Pe x (1- η_L)	Heat sink to ambient thermal resistance R _{hs-amb} (°C/W)	Heat sink to ambient temperature rise T _{hs-amb} (°C)
		xLED-BRI-8030	
5.0	5.00	5.00	25.0
10.0	3.80	3.80	38.0
15.0	3.27	3.27	49.0
20.0	3.00	3.00	60.0
25.0	2.76	2.76	69.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (T_{hs} - T_a) / P_d$

θ - Thermal Resistance [°C/W] ; T_{hs} - Heatsink temperature ; T_a - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is R_{junction-case}, the thermal resistance of the TIM outside the package is R_{interface (TIM)} [°C/W], the thermal resistance with the heat sink is R_{heatsink-ambient} [°C/W], and the ambient temperature is T_{ambient} [°C].

*Thermal resistances outside the package R_{interface (TIM)} and R_{heatsink-ambient} can be integrated into the thermal resistance R_{case-ambient} at this point. Thus, the following formula is also used:

$$T_{\text{junction}} = (R_{\text{junction-case}} + R_{\text{case-ambient}}) \cdot P_d + T_{\text{ambient}}$$